Product / Package Information

Package	LFCSP - Sawn
Body Size (mm)	8 X 8 X 0.75 (6.6 EP)
Lead Count	56
Terminal Finish	100 Sn
MS Number	MS010797B

Environmental Information

RoHS Compliant	Yes
High Temperature Compliant	Yes
Halogen Free Compliant	Yes
REACH SVHC Compliant	Yes

Materials Declaration

Molding Compound

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Other inorganic materials	Silica	60676-86-0	5.69E-02	86.91	869100	33.56	335632
Thermosets	Epoxy & Phenol Resin	Proprietary	8.37E-03	12.78	127800	4.94	49354
Other inorganic materials	Carbon black	1333-86-4	2.03E-04	0.31	3100	0.12	1197
Subtotal			6.55 E-02	100.00	1000000	38.62	386183

Leadframe

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Copper & its alloys	Copper	7440-50-8	8.81 E-02	97.5	975000	51.93	519338
Copper & its alloys	Iron	7439-89-6	2.12 E-03	2.35	23500	1.25	12517
Copper & its alloys	Zinc	7440-66-6	1.08 E-04	0.12	1200	0.06	639
Copper & its alloys	Phosphorus	7723-14-0	2.71 E-05	0.03	300	0.02	160
Subtotal			9.03 E-02	100.00	1000000	53.27	532654

Internal Leadframe Plating

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Precious metals	Silver	7440-22-4	1.85 E-03	100.0	1000000	1.09	10934

External Leadframe Plating

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Tin & its alloys	Tin	7440-31-5	3.90 E-04	100.0	1000000	0.23	2297

Bond Wires

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Precious metals	Gold	7440-57-5	1.01 E-03	99.0	990000	0.60	5952
Precious metals	Palladium	7440-05-3	1.02 E-05	1.0	10000	0.01	60
Subtotal			1.02 E-03	100.0	1000000	0.60	6013

Chip

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Other inorganic materials	Doped Silicon	7440-21-3	9.02 E-03	100.0	1000000	5.32	53213

Die Attach

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Precious metals	Silver	7440-22-4	1.16 E-03	77.71	777100	0.68	6813
Thermoset	Epichlorohydrin-formaldehyde-phenol copolymer	9003-36-5	4.62 E-05	3.11	31100	0.03	273
Other organic materials	Epoxy resin, epichlorohydrin-dimer fatty acid	68475-94-5	4.62 E-05	3.11	31100	0.03	273
Other organic materials	Butyrolactone, gamma-	96-48-0	4.62 E-05	3.11	31100	0.03	273
Other organic materials	Poly(oxypropylene)diamine	9046-10-0	4.62 E-05	3.11	31100	0.03	273
Other organic materials	2,6-Diglycidyl phenyl allyl ether oligomer	Unassigned	4.62 E-05	3.11	31100	0.03	273
Other organic materials	Organosilane	TS ref# 10001	4.62 E-05	3.11	31100	0.03	273
Other inorganic materials	Copper(II) oxide	1317-38-0	4.62 E-05	3.11	31100	0.03	273
Other organic materials	Epoxy resin modifier	TS ref# 10038	7.73 E-06	0.52	5200	0.005	46
Subtotal			1.49 E-03	100.0	1000000	0.88	8767

	Weight (g)	Percentage (%)	PPM
Package Totals	**1.70 E-01**	**100**	**1000000**

ANALOG DEVICES